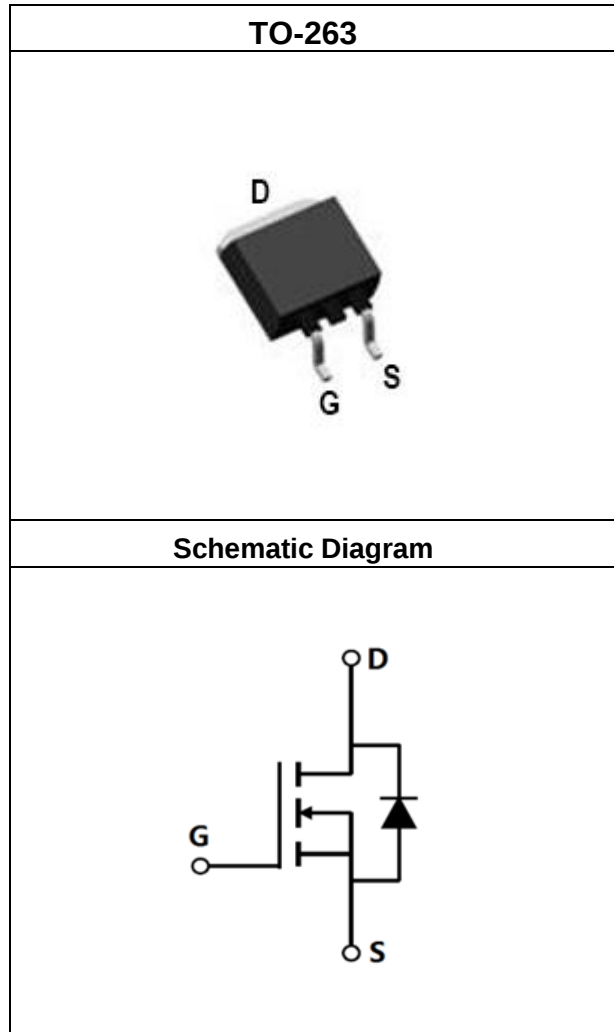


N-channel 30V, 1.2mΩ max., 300A
 SGT MOSFET S2 in TO-263

Datasheet – Production data

1. Descriptions

Key Performance Parameters



Parameters	Value	Unit
BV_{DSS}	30	V
$R_{DS(on),max}$	1.2	mΩ
$Q_{g,typ}$	108	nC
$I_{D,pulse}$	1200	A
E_{AS}	1156	mJ

Features

- Extremely low losses due to very low FOM $R_{DS(on)} \cdot Q_g$.
- High-speed switching.
- Qualified for industrial grade applications according to JEDEC.
- 100% UIS Tested.

Applications

High-Efficiency DC-DC Converters,
 High-Frequency Switching and Synchronous
 Rectification, Motor Drivers.

Type/Ordering Code	Package	Marking	Related Links
CSB012N03S2	TO-263	012N03S2	see Appendix A

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2. Maximum Ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 1. Absolute Maximum Ratings

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
V_{DS}	Drain-source voltage ¹⁾	-	-	30	V	$V_{GS}=0V$, $I_D=250\mu A$
I_D	Continuous drain current (Silicon Limited)	-	-	300	A	$T_C=25^\circ\text{C}$
$I_{D,pulse}$	Pulsed drain current	-	-	1200	A	$T_C=25^\circ\text{C}$
E_{AS}	Avalanche energy, single pulse ²⁾	-	-	1156	mJ	$I_D=68A$; $V_{DD}=50V$
I_{AS}	Avalanche current	-	-	68	A	-
V_{GS}	Gate source voltage	-20	-	20	V	static; AC ($f>1\text{ Hz}$)
P_{tot}	Power dissipation	-	-	375	W	$T_C=25^\circ\text{C}$
T_j, T_{stg}	Operating and storage temperature	-55	-	175	$^\circ\text{C}$	-
I_S	Continuous diode forward current	-	-	300	A	$T_C=25^\circ\text{C}$
$I_{S,pulse}$	Diode pulse current ²⁾	-	-	1200	A	$T_C=25^\circ\text{C}$

1) Limited by T_j max. Maximum duty cycle $D=0.75$.

2) $V_{DD}=50V$, $L=0.5mH$, $R_G=25\Omega$, Starting $T_j=25^\circ\text{C}$.

3. Thermal Characteristics

Table 2. Thermal Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
R_{thJC}	Thermal resistance, junction - case	-	-	0.4	°C/W	$T_C = 25^{\circ}\text{C}$
R_{thJA}	Thermal resistance, junction - ambient	-	-	65	°C/W	$T_C = 25^{\circ}\text{C}$
T_{sold}	Soldering temperature, wavesoldering only allowed at leads	-	-	260	°C	Lead Temperature (Soldering, 10 sec)

4. Electrical Characteristics

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Table 3. Static Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
$V_{(BR)DSS}$	Drain-source breakdown voltage	30	-	-	V	$V_{GS}=0V, I_D=250\mu A$
$V_{(GS)th}$	Gate threshold voltage	1.0	1.6	2.5	V	$V_{DS}=V_{GS}, I_D=250\mu A$
I_{DSS}	Zero gate voltage drain current	-	-	1	μA	$V_{DS}=30V, V_{GS}=0V, T_j=25^\circ C$
I_{GSS}	Gate-source leakage current	-	-	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
$R_{DS(on)}$	Drain-source on-state resistance	-	1.0	1.2	m Ω	$V_{GS}=10V, I_D=20A, T_j=25^\circ C$
R_G	Gate resistance	-	3.3	-	Ω	$V_{DD}=0V, V_{GS}=0V, F=1MHz$
g_{fs}	Transconductance		100		S	$V_{DS}=5V, I_D=20A$

Table 4. Dynamic Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
C_{iss}	Input capacitance	-	7000	-	pF	$V_{GS}=0V, V_{DS}=15V, f=250kHz$
C_{oss}	Output capacitance	-	3740	-	pF	$V_{GS}=0V, V_{DS}=15V, f=250kHz$
C_{rss}	Reverse transfer capacitance	-	334	-	pF	$V_{GS}=0V, V_{DS}=15V, f=250kHz$
$t_{d(on)}$	Turn-on delay time	-	20	-	ns	$V_{DD}=15V, V_{GS}=10V, I_D=40A, R_G=3\Omega$
t_r	Rise time	-	15	-	ns	$V_{DD}=15V, V_{GS}=10V, I_D=40A, R_G=3\Omega$
$t_{d(off)}$	Turn-off delay time	-	180	-	ns	$V_{DD}=15V, V_{GS}=10V, I_D=40A, R_G=3\Omega$
t_f	Fall time	-	60	-	ns	$V_{DD}=15V, V_{GS}=10V, I_D=40A, R_G=3\Omega$

Table 5. Gate Charge Characteristics

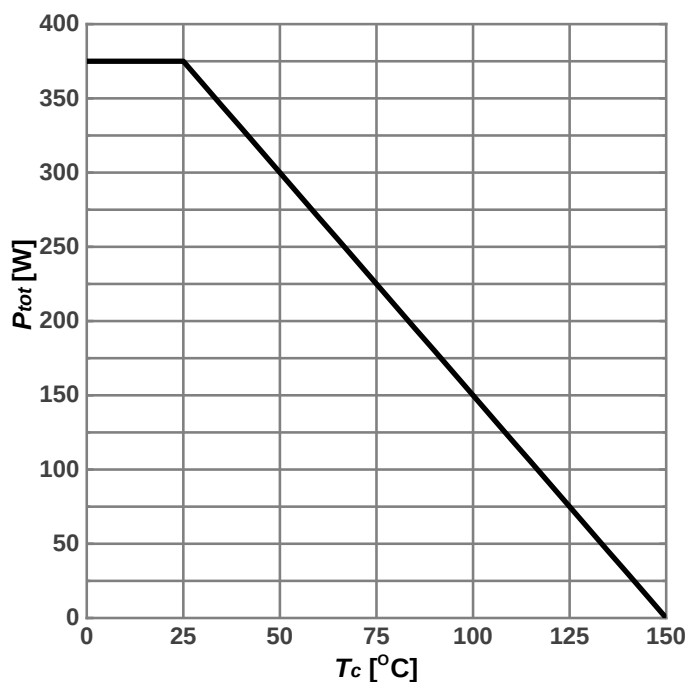
Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Q_{gs}	Gate to source charge	-	10.9	-	nC	$V_{DD}=15V, I_D=40A, V_{GS}=0 \text{ to } 10V$
Q_{gd}	Gate to drain charge	-	12.5	-	nC	$V_{DD}=15V, I_D=40A, V_{GS}=0 \text{ to } 10V$
Q_g	Gate charge total	-	108	-	nC	$V_{DD}=15V, I_D=40A, V_{GS}=0 \text{ to } 10V$
$V_{plateau}$	Gate plateau voltage	-	2.0	-	V	$V_{DD}=15V, I_D=40A, V_{GS}=0 \text{ to } 10V$

Table 6. Reverse Diode Characteristics

Symbol	Parameter	Values			Unit	Test Condition
		Min.	Typ.	Max.		
V_{SD}	Diode forward voltage	-	0.8	-	V	$V_{GS}=0V, I_F=40A, T_j=25^\circ C$
t_{rr}	Reverse recovery time	-	85	-	ns	$V_R=15V, I_F=40A, di_F/dt=100A/\mu s$
Q_{rr}	Reverse recovery charge	-	100	-	nC	$V_R=15V, I_F=40A, di_F/dt=100A/\mu s$
I_{rrm}	Peak reverse recovery current	-	3	-	A	$V_R=15V, I_F=40A, di_F/dt=100A/\mu s$

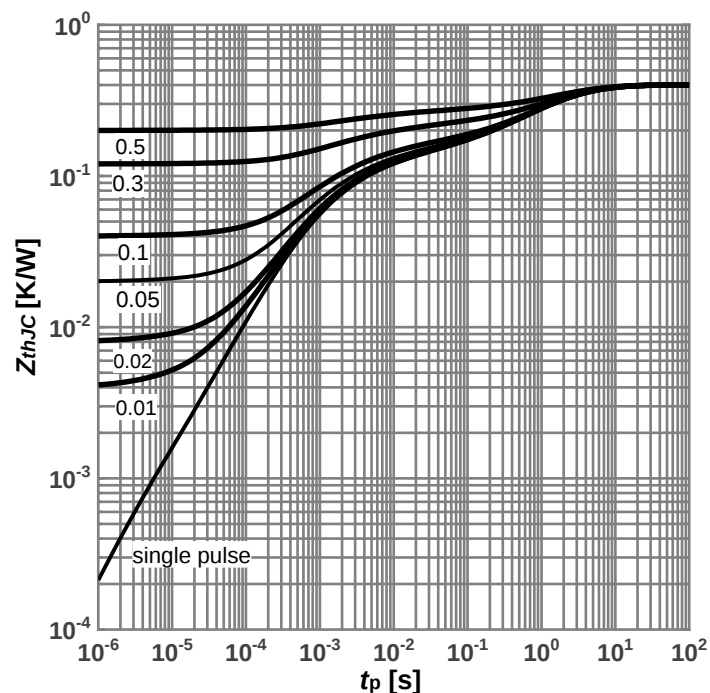
5. Electrical Characteristics Diagrams

Diagram 1: Power dissipation



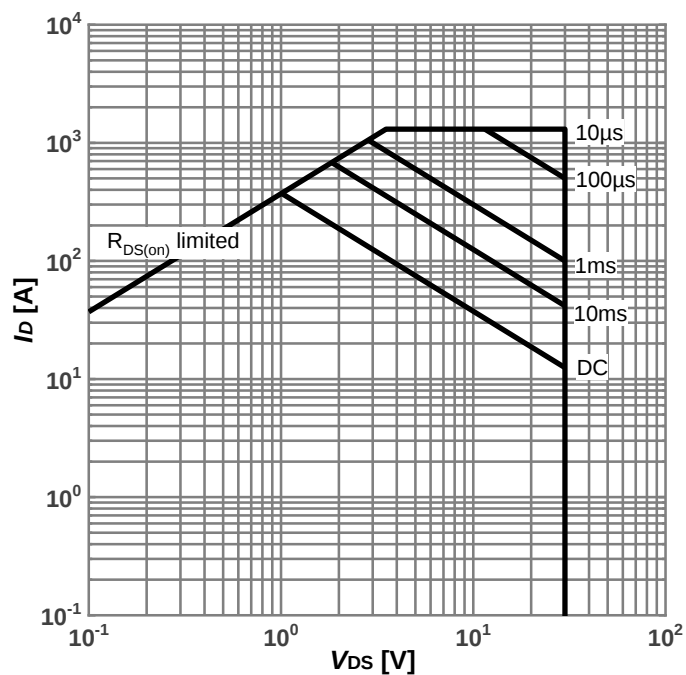
$$P_{tot}=f(T_c)$$

Diagram 2: Max. transient thermal impedance



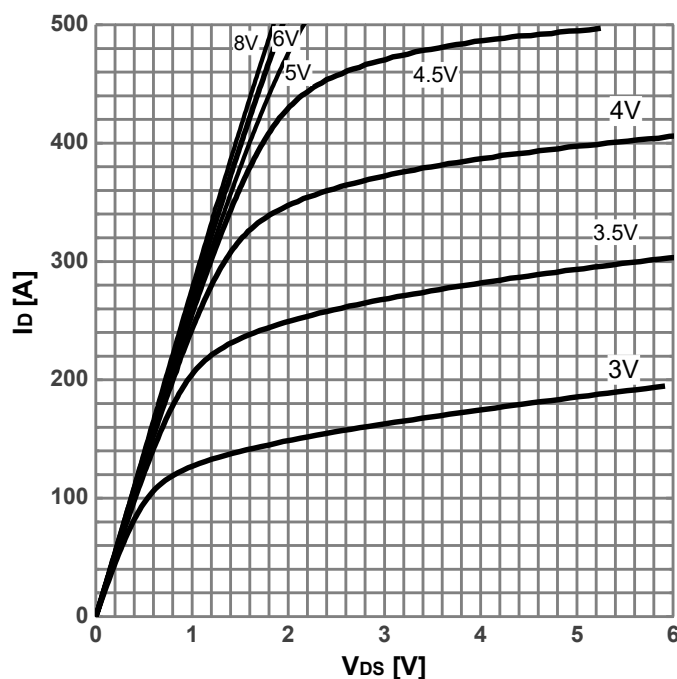
$$Z_{thJC}=f(t_p); \text{ parameter: } D = t_p/T$$

Diagram 3: Safe operating area



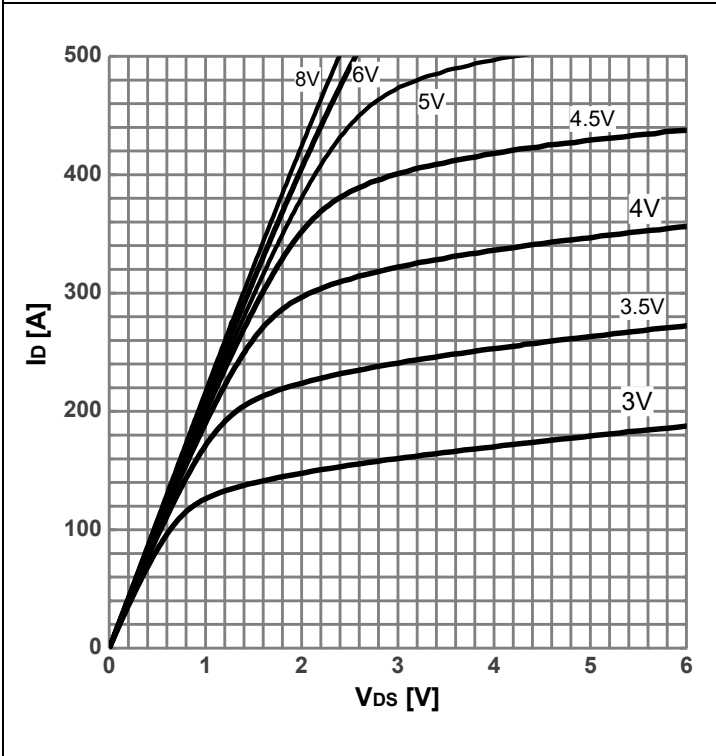
$$I_D=f(V_{DS}); T_J=25^\circ\text{C}; D=0; \text{ parameter: } t_p$$

Diagram 4: Typ. output characteristics



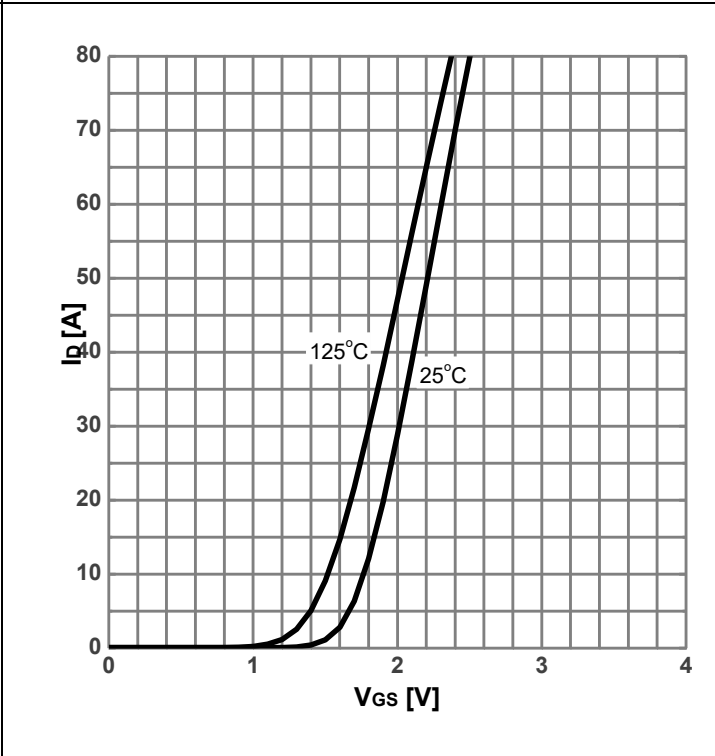
$$I_D=f(V_{DS}); T_J=25^\circ\text{C}; \text{ parameter: } V_{GS}$$

Diagram 5: Typ. output characteristics



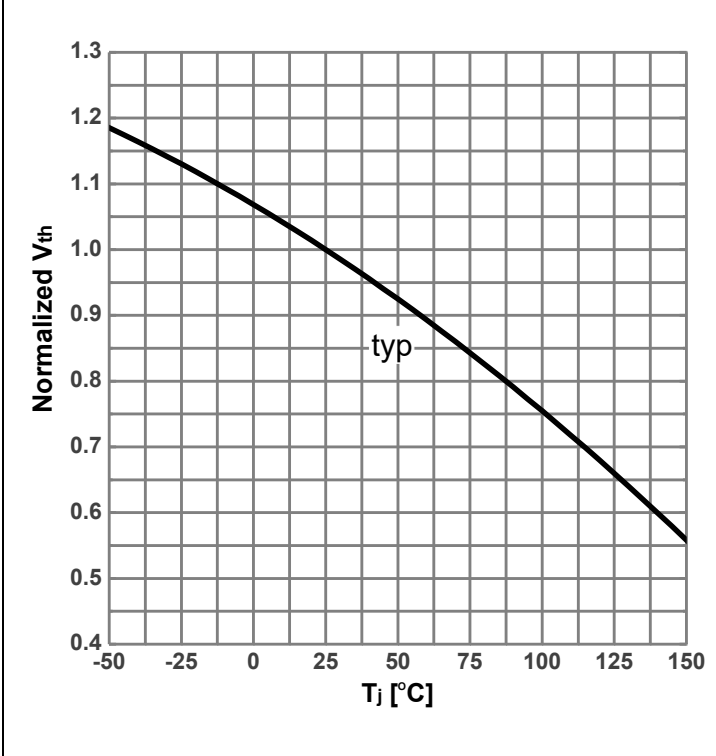
$I_D=f(V_{DS})$; $T_j=125^{\circ}\text{C}$; parameter: V_{GS}

Diagram 6: Typ. transfer characteristics



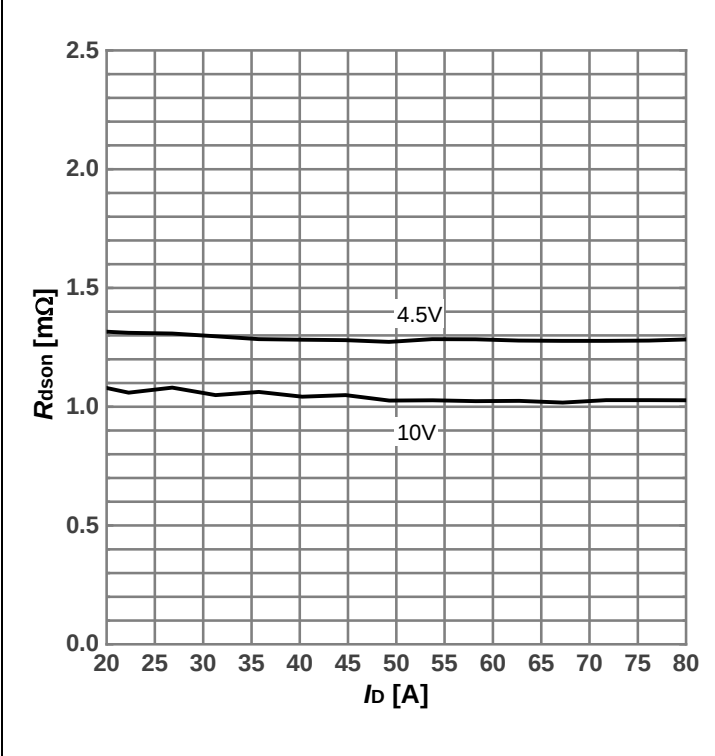
$I_D=f(V_{GS})$; $V_{DS}=15\text{V}$; parameter: T_j

Diagram 7: Gate threshold voltage vs. Junction temperature



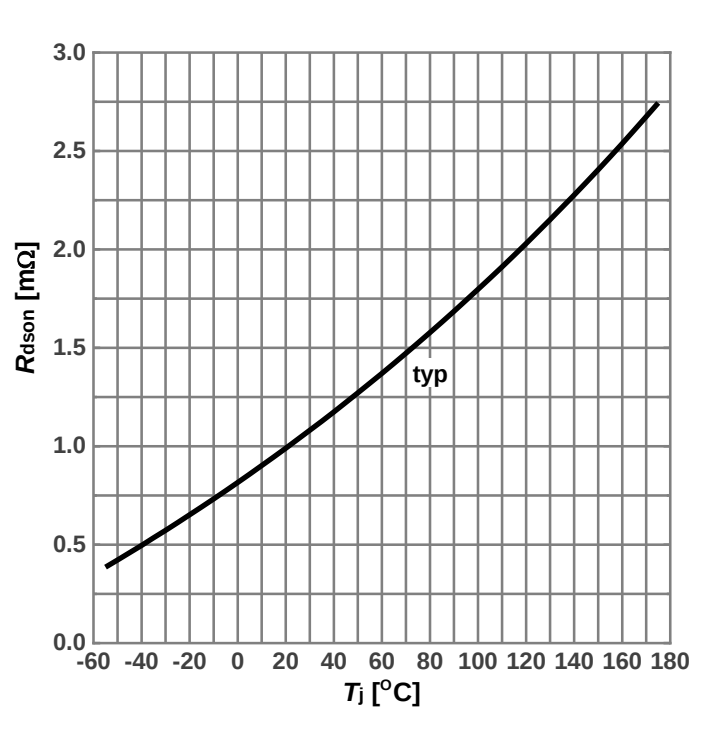
$V_{th}=f(T_j)$; $I_D=250\mu\text{A}$

Diagram 8: On-state resistance vs. Drain current



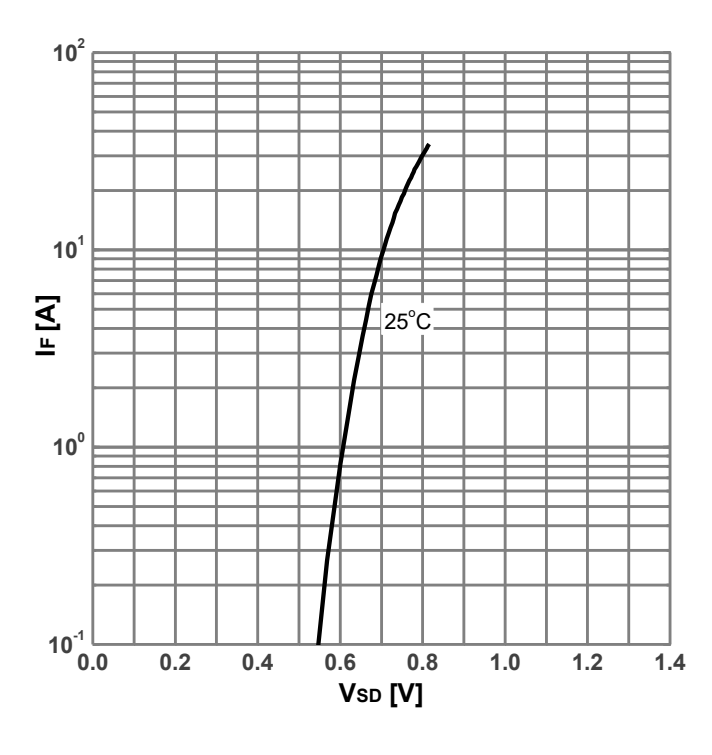
$R_{DS(on)}=f(I_D)$; $T_j=25^{\circ}\text{C}$; parameter: V_{GS}

Diagram 9: On-state resistance vs. Junction temperature



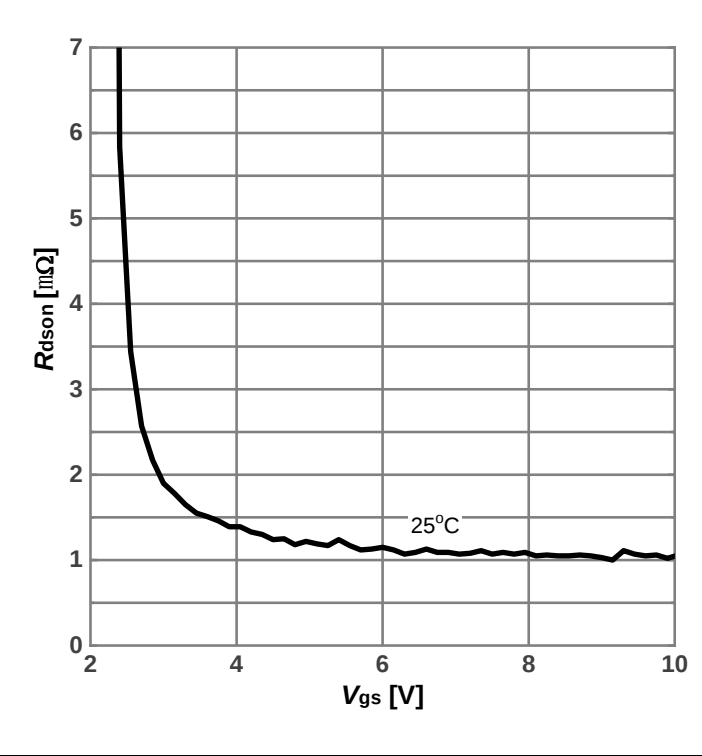
$R_{DS(on)}=f(T_j); I_D=20A; V_{GS}=10V$

Diagram 10: Forward characteristics of reverse diode



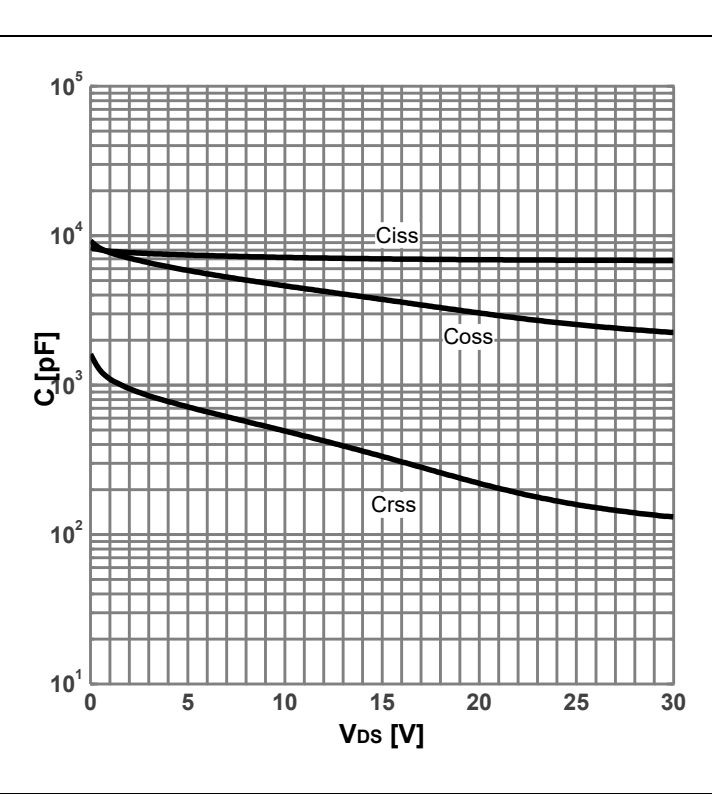
$I_F=f(V_{SD}); \text{parameter: } T_j$

Diagram 11: On-state resistance vs. Vgs characteristics

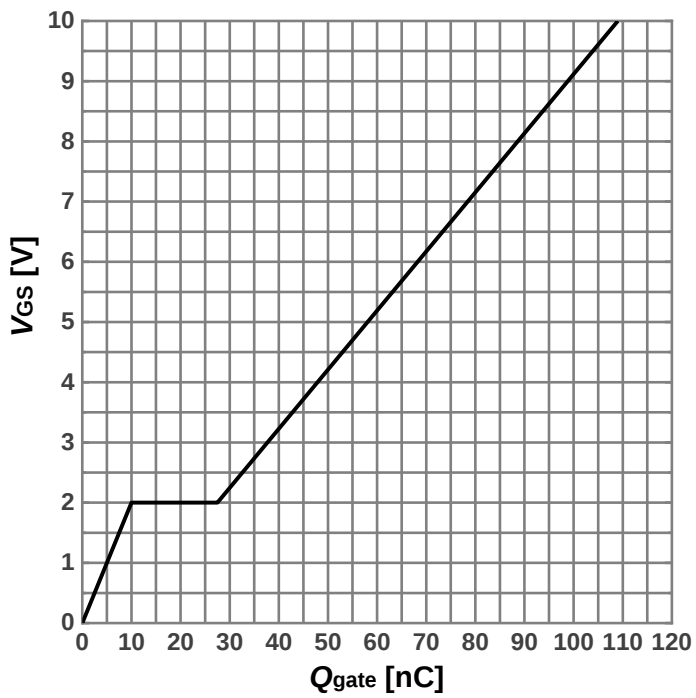


$R_{DS(on)}=f(V_{GS}); T_j=25^{\circ}C; I_D=20A$

Diagram 12: Typ. capacitances



$C=f(V_{DS}); V_{GS}=0V; f=250kHz$

Diagram 13: Typ. gate charge

$V_{GS}=f(Q_{gate})$; $I_D=40A$ pulsed; $V_{DS}=15V$

6. Test Circuits

Table 7. Diode Characteristics

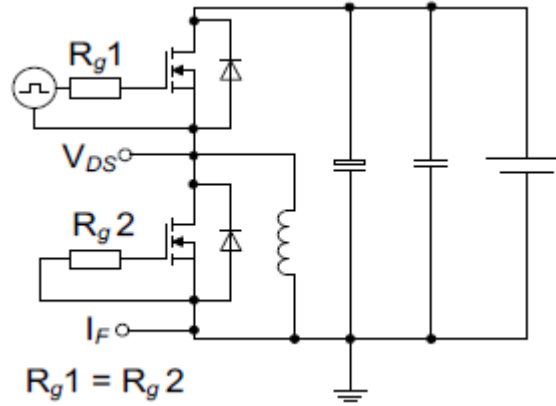
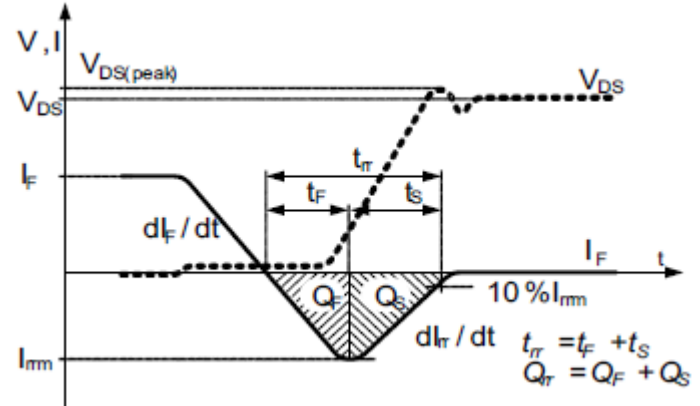
Test circuit for diode characteristics	Diode recovery waveform
	

Table 8. Switching Times

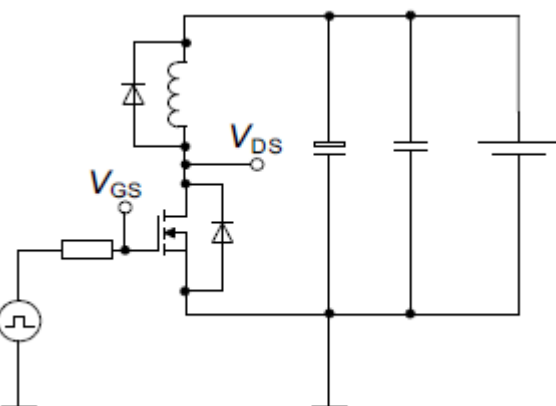
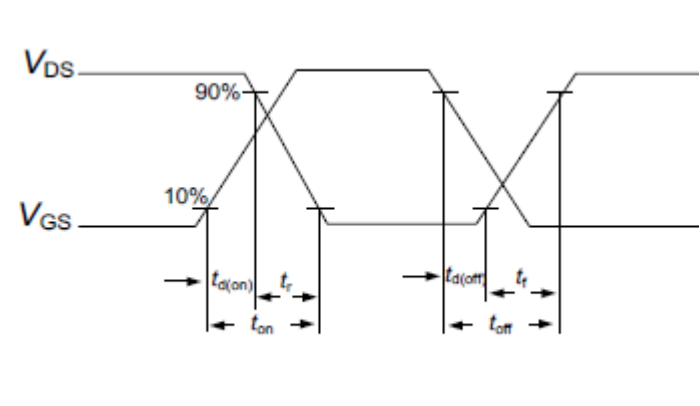
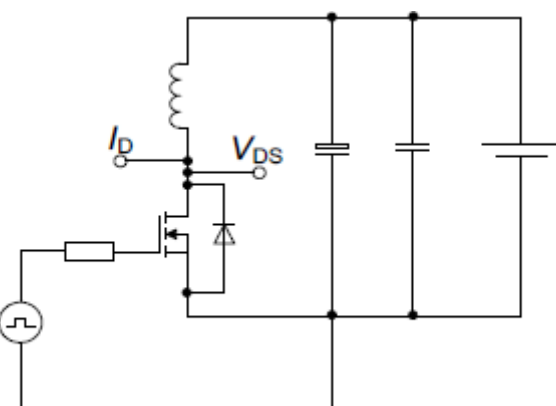
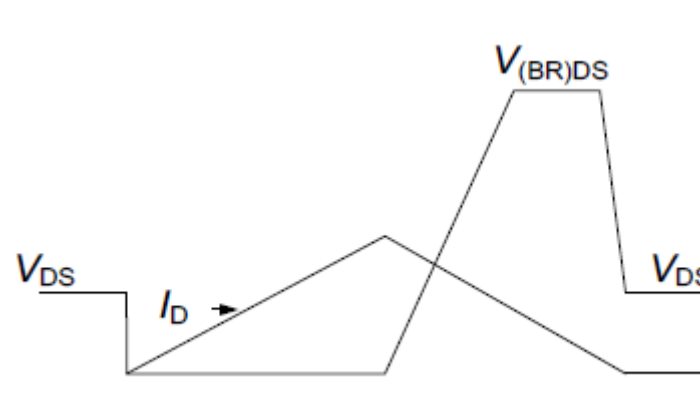
Switching times test circuit for inductive load	Switching times waveform
	

Table 9. Unclamped Inductive Load

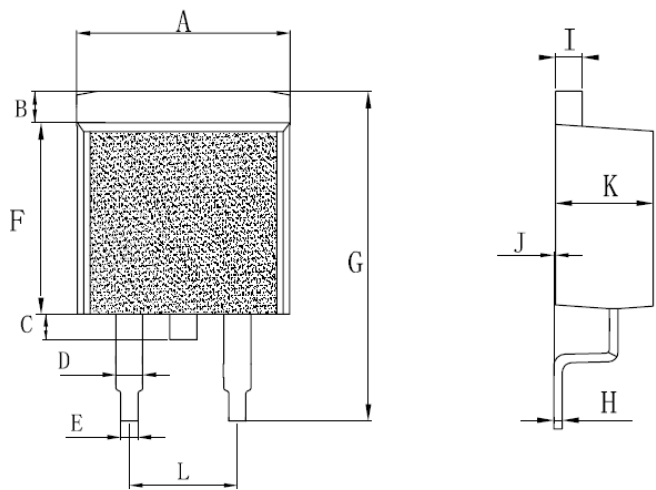
Unclamped inductive load test circuit	Unclamped inductive waveform
	

7. Package Outlines

Figure 1 Outline TO-263 Dimensions in mm

PACKAGE OUTLINE DIMENSIONS

TO-263



DIM.	Unit(mm)		Unit(inch)	
	Min	Max	Min	Max
A	9.7	10.4	0.381	0.409
B	1.31	1.62	0.051	0.063
C	0.65	1.22	0.025	0.048
D	1.15	1.36	0.045	0.053
E	0.62	0.95	0.024	0.037
F	8.75	9.32	0.344	0.366
G	14.75	15.8	0.580	0.622
H	0.32	0.48	0.012	0.018
I	1.18	1.36	0.046	0.053
J	0	0.15	0	0.005
K	4.38	4.86	0.172	0.191
L	4.85	5.23	0.190	0.205

8. Appendix

CoolSemi Webpage: www.coolsemi.com.